

Title (en)

DEVICE AND METHOD FOR GRINDING A PROFILE

Title (de)

VORRICHTUNG UND VERFAHREN ZUM SCHLEIFEN EINES PROFILS

Title (fr)

DISPOSITIF ET PROCÉDÉ POUR RECTIFIER UN PROFIL

Publication

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Application

EP 21820140 A 20211123

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Abstract (en)

[origin: WO2022135814A2] The invention relates to a method and a device (1) for using a grinding element to grind a profile of a rail track intended for rail-bound vehicles. The support is arranged on the device (1) for translatory movement in a plane transverse to the profile by means of a guide (12) and can be applied against the profile by a contact element (13, 14) such that the support carrying the grinding element automatically aligns itself in the transverse plane in respect of the profile and in respect of the device (1). Furthermore, the support for the grinding element can be moved in a translatory oscillating manner parallel to a longitudinal axis of the profile during rotational movement, such that a profile section is worked by the grinding element multiple times and the grinding outcome is substantially improved by the translatory movement.

IPC 8 full level

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